

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Curran, et al.

Serial No: To be Assigned

Conf. No: To be Assigned

Filed: 10/26/2001

For: METHOD AND SYSTEM FOR REDUCING THICKNESS OF SPIN-ON GLASS ON SEMICONDUCTOR WAFERS

Docket No. 11-29038

Examiner: TBD

Art Unit: TBD

Assistant Commissioner for Patents
Washington, DC 20231

"EXPRESS MAIL" Mailing Label No. EL645458870US.

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service with sufficient postage for "Express Mail Post Office to Addressee" service under 37 CFR 1.10 and is addressed to: Assistant Commissioner for Patents, Washington, DC 20231 on

10-26-01.

Ann Trent

Ann Trent

PRELIMINARY AMENDMENT

Dear Sir:

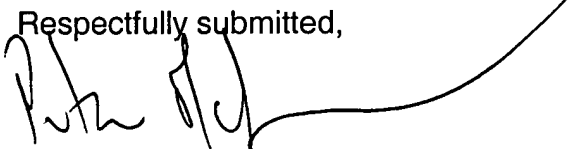
Prior to the examination of the above identified application, please amend the specification by inserting before the first line the sentence:

A1 This application claims priority under 35 USC § 119(e)(1) of provisional application Serial No. 60/248,170, filed November 13, 2000.

Should the Examiner have any comments or suggestions concerning this application, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

To the extent necessary, Applicants petition for an Extension of Time under 37 CFR 1.136. Please charge any fees in connection with the filing of this paper, including extension of time fees, to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

Respectfully submitted,



Peter K. McLarty
Agent for Applicants
Reg. No. 44,923

Texas Instruments Incorporated
Mail Station 3999
P.O. Box 655474
Dallas, TX 75265
(972) 917-4258

TI-29038-00001